

**IN THE CLAIMS:**

Please cancel claims 1-5 without prejudice or disclaimer of the subject matter thereof.

The following is a complete listing of claims in this application.

Claims 1-5 (canceled).

6. (new) A method for manufacturing a plurality of metal core substrates for a surface-mounted light emitting diode, comprising the steps of:

preparing a plurality of metal base plates and a plurality of insulation layers;

adhering a pair of metal base plates and a plurality of insulation layers;

adhering a pair of metal base plates interposing one of the insulation layers as a first insulation layer to form a set plate;

stacking a plurality of set plates at a position between a pair of guide plates, interposing a separation gap between adjacent set plates to form a set plate block;

cutting the set plate block in a stacking direction along lines corresponding to a predetermined height of the metal base to form a set plate aggregation;

securing a second insulation layer to a cut surface of the set plate aggregation;

securing a circuit pattern aggregation layer to the second insulation layer to form a metal core substrate aggregation;

forming a separation groove on the circuit pattern aggregation layer between adjacent set plates, corresponding to the separation gap;

forming a groove along a center line of the set plate to separate the set plate into first and second circuit pattern aggregations;

forming electrodes on both sides of the substrate aggregation;

separating the guide plates; and

cutting off the substrate aggregation into independent substrates.

7. (new) A method according to claim 6, further comprising a step of forming a plurality of through-holes in each of the circuit pattern aggregations.

8. (new) A method for manufacturing a plurality of metal core substrates for a surface-mounted light emitting diode, comprising the steps of:

preparing a plurality of metal base plates and a plurality of insulation layers;

adhering a pair of metal base plates interposing one of the insulation layers as a first insulation layer by thermocompression to form a set plate;

stacking a plurality of set plates at a position between a pair of guide plates, interposing a separation gap between adjacent set plates to form a set plate block;

cutting the set plate block in a stacking direction along lines corresponding to a predetermined height of the metal base to form a set plate aggregation;

securing a second insulation layer to a cut surface of the set plate aggregation to form a metal core substrate aggregation;

forming an electrolytic gold plating surface on the metal core substrate aggregation.